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Substrate: 1.59mm  $\pm 0.18$ mm [0.0625"  $\pm 0.007$ "] per IPC 4101/21, gold surface finish.



Substrate: 3.18mm  $\pm 0.18$ mm  $[0.125" \pm 0.007"]$  FR4/G10 or equivalent high temp material. Non-clad.



Leads: material- phosphor bronze; plating- Sn96 Ag4 solid



Pins: shell material- Brass Alloy 360 1/2 hard; finish-  $0.25\mu m$  [ $10\mu$ "] Au over  $1.27\mu m$  [ $50\mu$ "] Ni (min.). Contact material- BeCu; finish  $0.25\mu m$  [ $10\mu$ "] Au over  $2.54\mu m$  [ $100\mu$ "] Ni (min.).



Test points: material- Phosphor Bronze; plating-Sn over 1.27µm [50µ"] Ni. Gold flash on contact end.

**ROHS COMPLIANT** 

Description: Carrier Adaptor (CA)

20 position ZIF socket to 20 position SOIC surface-mountable foot

with test points. Pin mapping is 1:1

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

CA-SO20A-Z-J-T-01F Drawing		Status: Released	Scale: 2:1		Rev: A
	© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 1/8/06	
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